

CLAIMS

What is claimed is:

- 5 1. A method for forming a component, comprising the steps of:
- forming a set of substructures for the component;
- 10 forming an airdome structure that encloses the substructures and that provides a set of air spaces for providing isolation among the substructures.
2. The method of claim 1, wherein the step of forming an airdome structure includes the step of
- 15 forming the air spaces in the airdome structure.
3. The method of claim 2, wherein the step of forming the air spaces includes the steps of:
- depositing a layer of dielectric material;
- 20 forming a top substructure onto the layer of photo-resist;
- forming a set of gaps in the top substructure;
- removing the layer of photo-resist underneath the top substructure.
- 25 4. The method of claim 3, wherein the step of forming an airdome structure includes the step of depositing an overcoat on the top substructure such that the overcoat seals the gaps and encloses the air
- 30 spaces.
5. The method of claim 4, wherein the step of depositing an overcoat includes the step of

depositing a dielectric material.

6. The method of claim 4, wherein the step of
depositing an overcoat includes the step of
5 depositing a plastic material.

7. The method of claim 4, wherein the step of
depositing an overcoat includes the step of
depositing an organic material.
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8. The method of claim 4, wherein the step of
forming a top substructure includes the step of
shaping the top substructure to impede the overcoat
from entering the air spaces.
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9. The method of claim 8, wherein the step of
shaping the top substructure includes the step of
shaping the layer of photo-resist.

20 10. A component, comprising:
a set of substructures;
an airdome structure that encloses the
substructures and that provides a set of air spaces
for providing isolation among the substructures.

25 11. The component of claim 10, wherein the
substructures include a top substructure having a set
of gaps.

30 12. The component of claim 11, wherein the airdome
structure includes an overcoat that seals the gaps
and encloses the air spaces.

13. The component of claim 12, wherein the overcoat is a dielectric material.

14. The electronic component of claim 12, wherein
5 the overcoat is a plastic material.

15. The component of claim 12, wherein the overcoat is an organic material.

10 16. The component of claim 12, wherein the top substructure is shaped to impede the overcoat from entering the air spaces during formation.